

APPENDIX D

Screening Guides

The following screening procedures are suggested guides for assemblies and their components:

- HRP 101: Screening Guide for Discrete Diodes
- HRP 102: Screening Guide for Finished Bridge Rectifier Assemblies
- HRP 103: Screening Guide for Capacitors Used in Multiplier Assemblies
- HRP 104: Screening Guide for Resistors Used in Multiplier Assemblies
- HRP 105: Screening Guide for Multiplier Assemblies
- HRP 106: Screening Guide for Hi-rel Hybrid Multiplier Assemblies

HRP 101: Discrete Diodes

The following screening for discrete diodes is a guide for a suggested procedure. It can be modified or adjusted to suit requirements. This is taken from MIL-PRF-19500 Table IV, JANTX screening.

1)	High Temperature Life (non-operating life/ stabilization bake MIL-STD-750)	Method 1032	48 hrs @ +175°C
2)	Temperature Cycling MIL-STD-750	Method 1051 Condition C	20 Cycles -65°C to +175°C 15 min. extremes No dwell @25°C
3)	Interim Electrical		Forward Voltage Drop Leakage Current
4)	High Temperature Reverse Bias (HTRB) MIL-STD-750	Method 1038 Condition A	96 hrs min. @ TA=150°C and min. applied voltage at 80% of rated VR (TC or TL is optional)
5)	Final Electrical MIL-STD-750	Method 4011 Method 4016 Method 4031 Method 4021	Forward Voltage Drop Leakage Current Reverse Recovery Time Peak Inverse Voltage